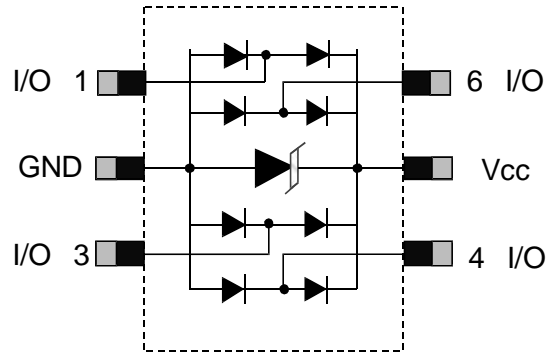


### Features

- 40Watts peak pulse power ( $t_p = 8/20\mu s$ )
- SOT-363 package
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- Low capacitance ( $C_j = 0.25pF$  typ.)
- Protection one data/power line
- IEC 61000-4-2  $\pm 15kV$  contact  $\pm 20kV$  air
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 3.5A (8/20 $\mu s$ )



### Applications

- Ethernet
- Digital Visual Interface
- (DVI) USB2.0
- Notebook and PC
- Computers

**Absolute Maximum Rating**

Rating	Symbol	Value	Units
Peak Pulse Power ( $t_p=8/20\mu s$ )	$P_{PP}$	40	Watts
Peak Pulse Current ( $t_p=8/20\mu s$ )(note1 )	$I_{PP}$	3.5	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	$V_{ESD}$	20 15	kV
Lead Soldering Temperature	$T_L$	260(10seconds)	$^{\circ}C$
Junction Temperature	$T_J$	-55 to + 125	$^{\circ}C$
Storage Temperature	$T_{stg}$	-55 to + 125	$^{\circ}C$

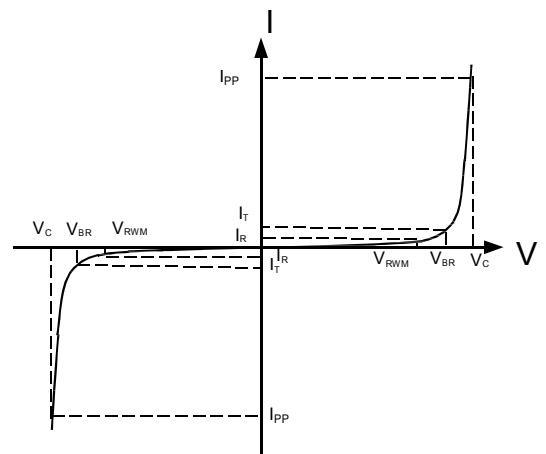
**Electrical Characteristics**

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	$V_{RWM}$				5.0	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T=1mA$	6			V
Reverse Leakage Current	$I_R$	$V_{RWM}=5V, T=25^{\circ}C$		50	500	nA
Peak Pulse Current	$I_{PP}$	$t_p=8/20\mu s$			3	A
Clamping Voltage	$V_C$	$I_{PP}=3.5A, t_p=8/20\mu s$		9	13	V
Junction Capacitance	$C_j$	$V_R = 0V, f = 1MHz$ IO to IO		0.2	0.25	pF
		$V_R = 0V, f = 1MHz$ IO to GND		0.35	0.4	

**Electrical Parameters (TA = 25°C unless otherwise noted)**

Symbol	Parameter
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current

Note: 8/20μs pulse waveform.



Typical Characteristic Curves

Fig.1 Peak Pulse Power Rating Curve

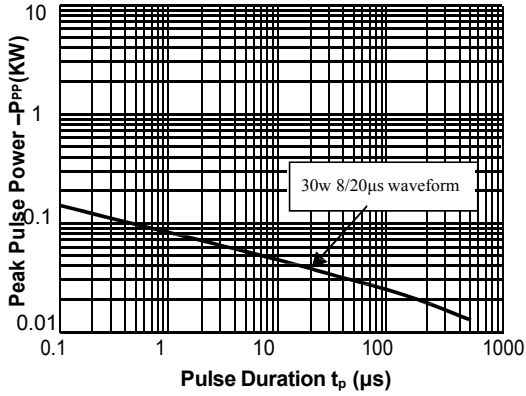


Fig.2 Pulse Derating Curve

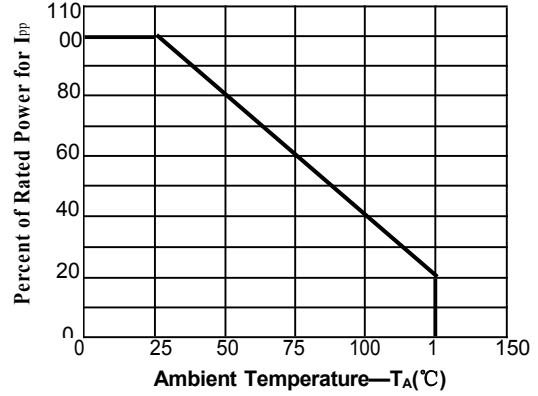


Fig.3 Pulse Waveform-8/20 $\mu$ s

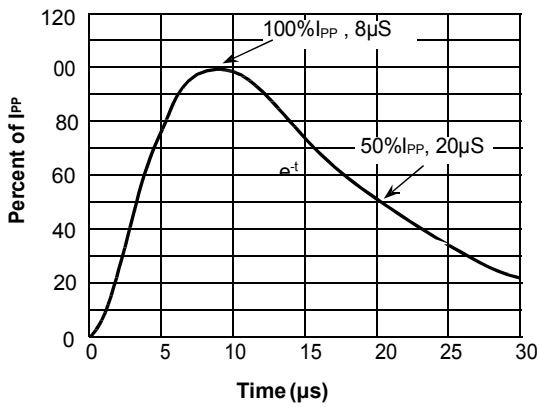


Fig.4 Pulse Waveform-ESD(IEC61000-4-2)

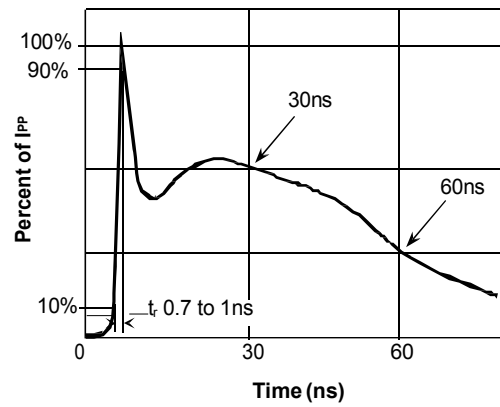
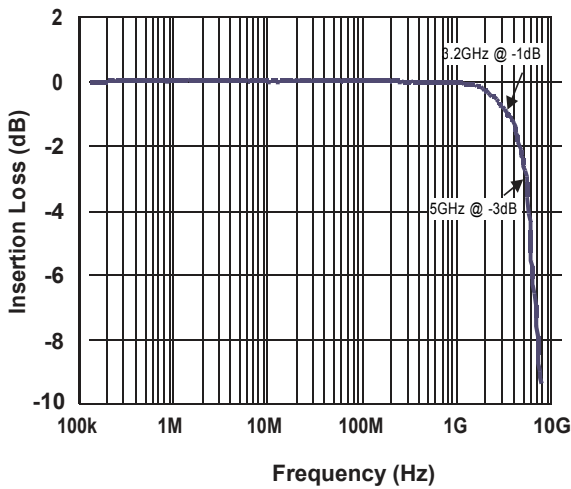
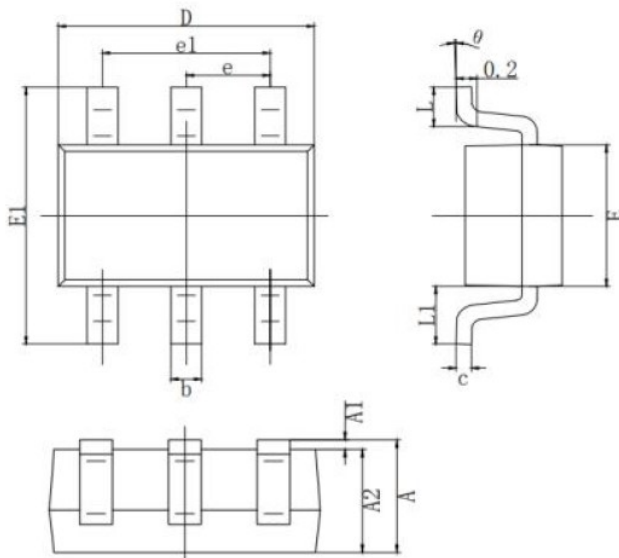


Fig.5 Insertion Loss S21 - I/O to GND

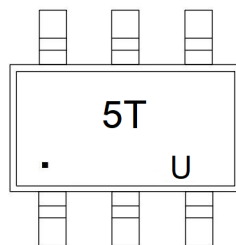


**SOT-363 PACKAGE OUTLINE DIMENSIONS**



SYMBOL	MILLIMETER	
	MIN	MAX
A	0.900	1.100
A1	0.000	0.100
A2	0.900	1.000
b	0.150	0.350
c	0.080	0.150
D	2.000	2.200
E	1.150	1.350
E1	2.150	2.450
e	0.650 TYP.	
e1	1.200	1.400
L	0.525 REF.	
L1	0.260	0.460
θ	0°	8°

**Marking**



**Ordering information**

Order code	Package	Base qty	Delivery mode
UMW BST363A054U	SOT-363	3000	Tape and reel

单击下面可查看定价，库存，交付和生命周期等信息

[>>UMW\(友台半导体\)](#)